

H11AG1

H11AG2

H11AG3

DESCRIPTION

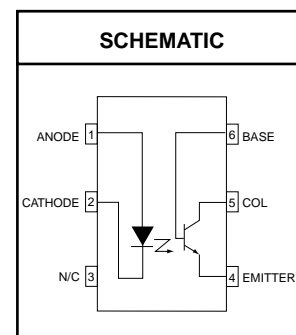
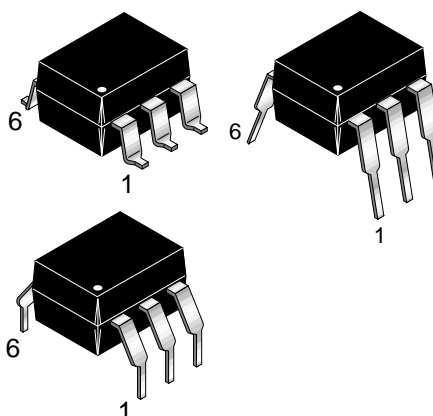
The H11AG series consists of a Gallium-Aluminum-Arsenide IRED emitting diode coupled with a silicon phototransistor in a dual in-line package. This device provides the unique feature of the high current transfer ratio at both low output voltage and low input current. This makes it ideal for use in low power logic circuits, telecommunications equipment and portable electronics isolation applications.

FEATURES

- High efficiency low degradation liquid epitaxial IRED
- Logic level compatible, input and output currents, with CMOS and LS/TTL
- High DC current transfer ratio at low input currents
- Underwriters Laboratory (UL) recognized File #E90700

APPLICATIONS

- CMOS driven solid state reliability
- Telephone ring detector
- Digital logic isolation



ABSOLUTE MAXIMUM RATINGS

Parameters	Symbol	Device	Value	Units
TOTAL DEVICE				
Storage Temperature	T _{STG}	All	-55 to +150	°C
Operating Temperature	T _{OPR}	All	-55 to +100	°C
Lead Solder Temperature	T _{SOL}	All	260 for 10 sec	°C
Total Device Power Dissipation @ 25°C (LED plus detector) Derate Linearly From 25°C	P _D	All	260	mW
			3.5	mW/°C
EMITTER				
Continuous Forward Current	I _F	All	50	mA
Reverse Voltage	V _R	All	6	V
Forward Current - Peak (1 μs pulse, 300 pps)	I _F (pk)	All	3.0	A
LED Power Dissipation 25°C Ambient Derate Linearly From 25°C	P _D	All	75	mW
			1.0	mW/°C
DETECTOR				
Detector Power Dissipation @ 25°C Derate Linearly from 25°C	P _D	All	150	mW
			2.0	mW/°C
Continuous Collector Current		All	50	mA

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ELECTRICAL CHARACTERISTICS (T_A = 0-70°C Unless otherwise specified.)

INDIVIDUAL COMPONENT CHARACTERISTICS

Parameters	Test Conditions	Symbol	Device	Min	Typ	Max	Units
EMITTER							
Input Forward Voltage	I _F = 1 mA	V _F	All			1.5	V
Reverse Leakage Current	V _R = 5 V, T _A = 25°C	I _R	All			10	μA
	V _R = 5 V, T _A = 70°C	I _R	All			100	μA
Capacitance	V = 0, f = 1.0 MHz	C _J	All			100	pF
DETECTOR							
Breakdown Voltage							
Collector to Emitter	I _C = 1.0 mA, I _F = 0	BV _{CEO}	All	30			V
Collector to Base	I _C = 100 μA, I _F = 0	BV _{CBO}	All	70			V
Emitter to Collector	I _C = 100 μA, I _F = 0	BV _{ECO}	All	7			V
Leakage Current							
Collector to Emitter	V _{CE} = 10 V, I _F = 0	I _{CEO}	All		5	10	μA
Capacitance	V _{CE} = 10 V, f = 1 MHz	C _{CE}	All		2		pF

ISOLATION CHARACTERISTICS

Parameters	Test Conditions	Symbol	Min	Typ	Max	Units
Input-Output Isolation Voltage	I _{I-0} ≤ 1 μA, t = 1 min.	V _{ISO}	5300			Vac(rms)

TRANSFER CHARACTERISTICS (T_A = 25°C Unless otherwise specified.)

DC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
Current Transfer Ratio	I _F = 1 mA, V _{CE} = 5 V	CTR	H11AG1	300			%
			H11AG2	200			
			H11AG3	100			
	I _F = 1 mA, V _{CE} = 0.6 V	CTR	H11AG1	100			
			H11AG2	50			
			H11AG3	20			
	I _F = 0.2 mA, V _{CE} = 1.5 V	CTR	H11AG1	100			
			H11AG2	50			
Saturation Voltage	I _F = 2.0 mA, I _C = 0.5 mA	V _{CE(SAT)}	All			.40	V
AC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
Non-Saturated Switching Times							
Turn-On Time	R _L = 100 Ω, I _F = 1 mA, V _{CC} = 5 V	t _{on}	All		5		μS
Turn-Off Time	R _L = 100 Ω, I _F = 1 mA, V _{CC} = 5 V	t _{off}	All		5		μS

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Figure 1. LED Forward Voltage vs. Forward Current

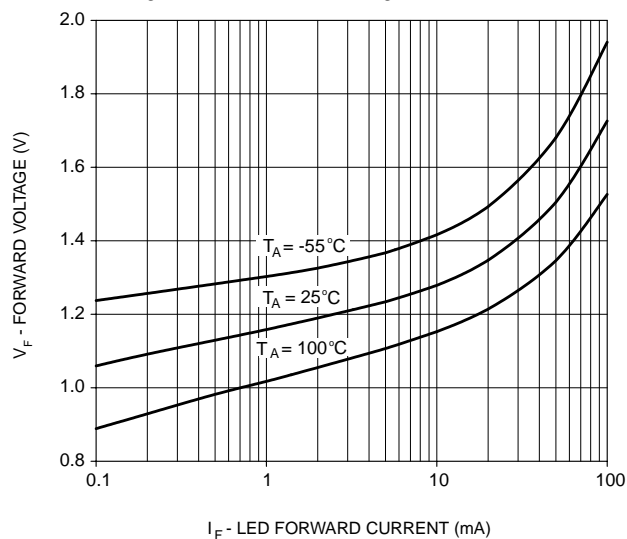


Figure 2. Normalized Current Transfer Ratio vs. Forward Current

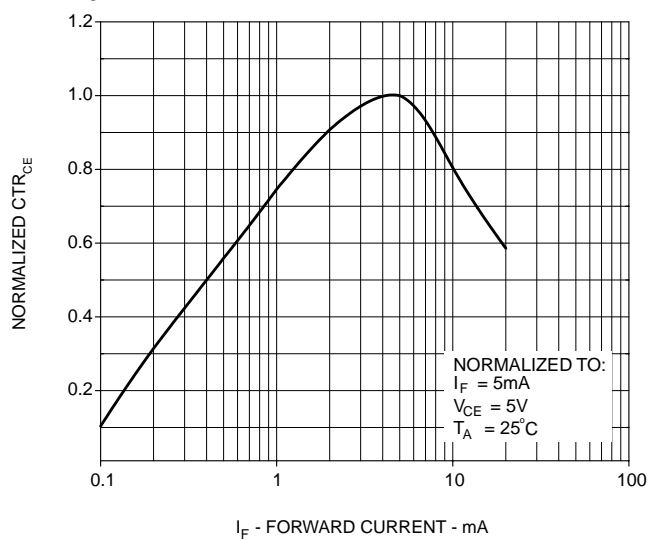


Figure 3. Normalized CTR vs. Temperature

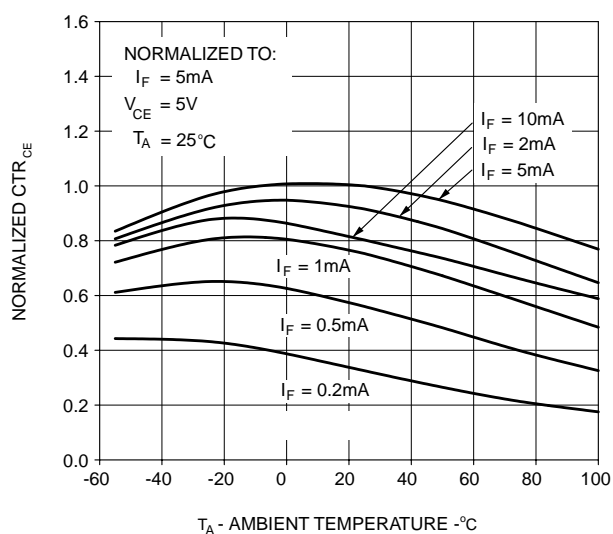
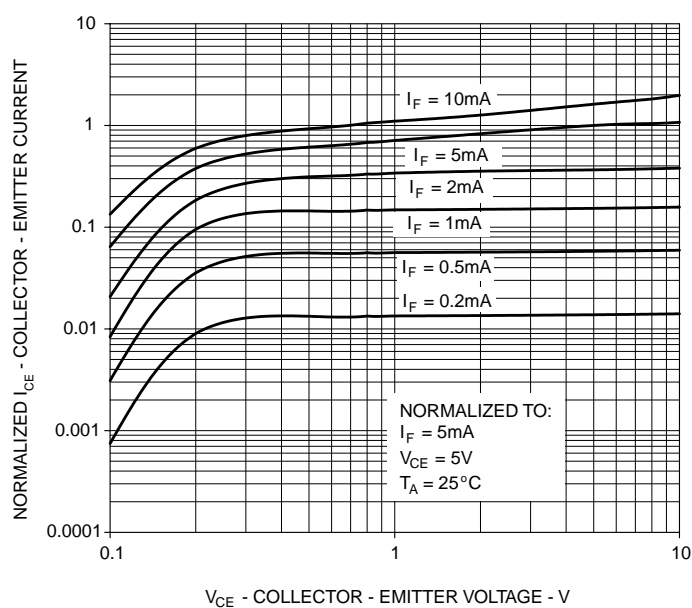


Figure 4. Normalized Collector vs. Collector - Emitter Voltage



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Figure 5. Normalized Collector Base Photocurrent Ratio vs. Forward Current

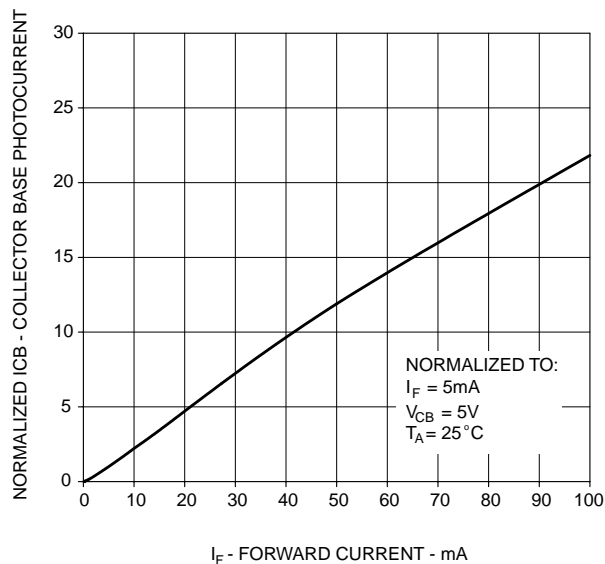


Figure 6. Normalized Collector - Base Current vs. Temperature

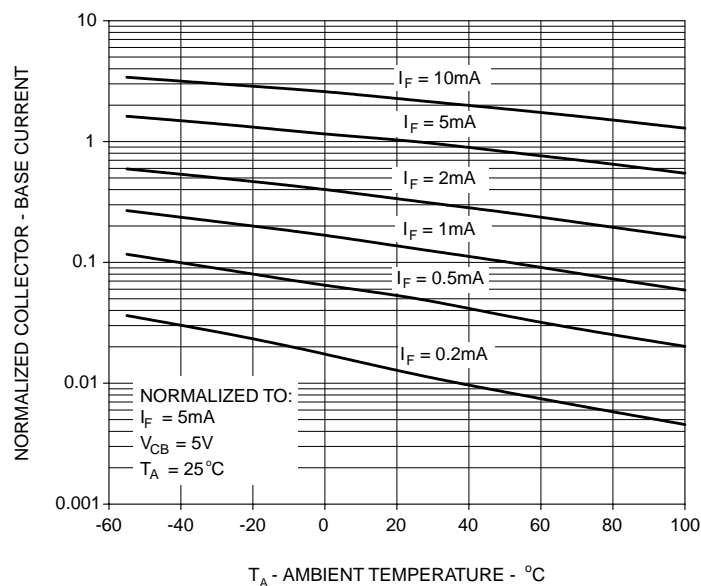
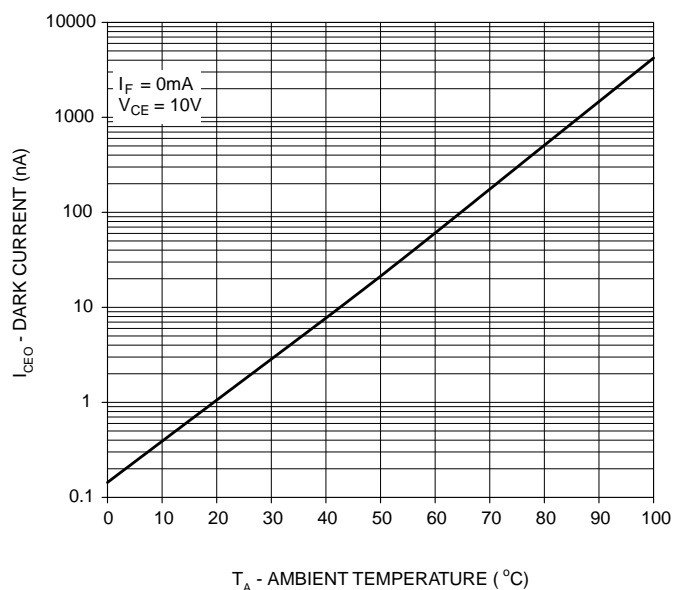


Figure 7. Collector-Emitter Dark Current vs. Ambient Temperature



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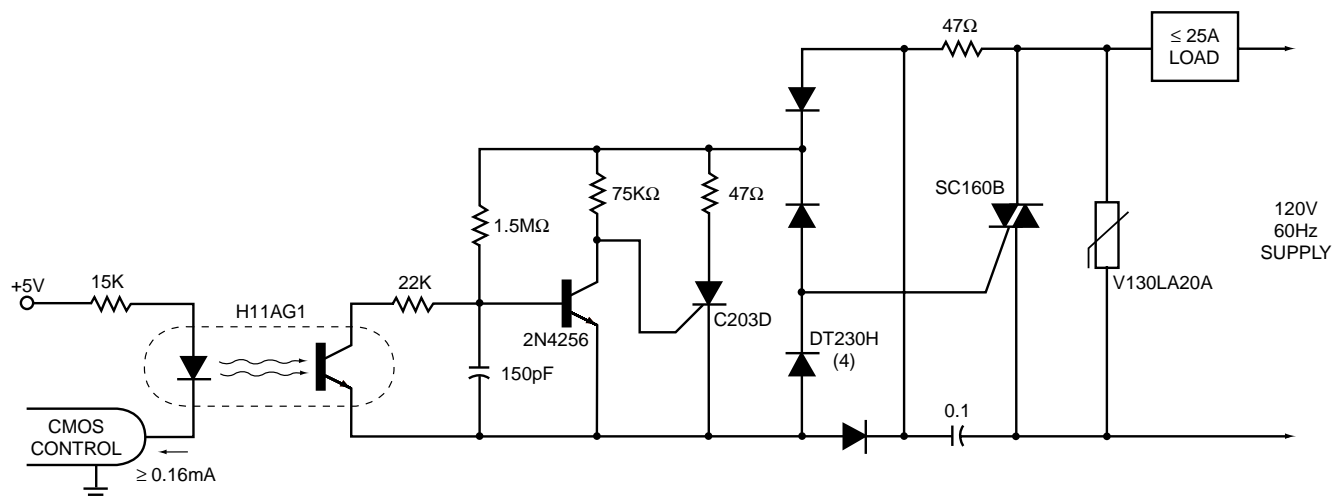
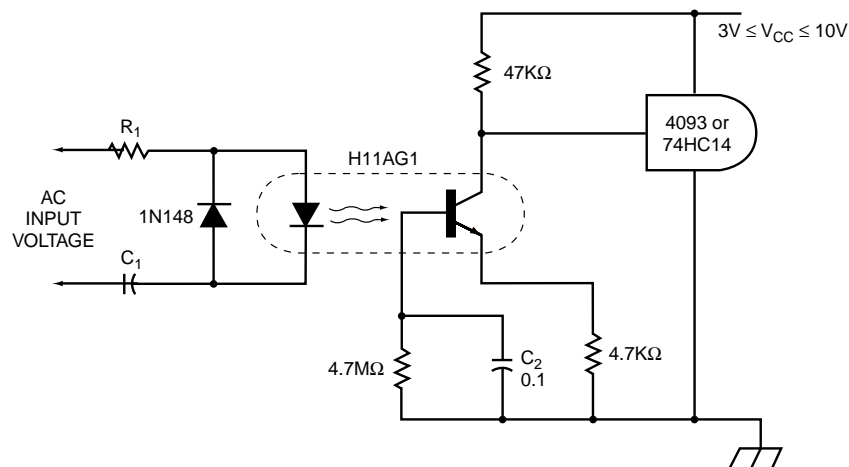


Figure 8. CMOS Input, 3KW, Zero Voltage Switching Solid State Relay

The H11AG1's superior performance at low input currents allows standard CMOS logic circuits to directly operate a 25A solid state relay. Circuit operation is as follows: power switching is provided by the SC160B, 25A triac. Its gate is controlled by the C203B via the DT230H rectifier bridge. The C203B turn-on is inhibited by the 2N4256 when line voltage is above 12V and/or the H11AG is off. False trigger and dv/dt protection are provided by the combination of the MOV® varistor and RC snubber network.



INPUT	R ₁	C ₁	Z
40-90 VRMS 20 Hz	75 K 1/10 W	0.1 μF 100 V	109K
95-135 VRMS 60 Hz	180 K 1/10 W	12 nF 200 V	285K
200-280 VRMS 50/60 Hz	390 K 1/4 W	6.80 nF 400 V	550K

DC component of input voltage is ignored due to C1

Figure 9. Telephone Ring Detector/A.C. Line CMOS Input Isolator

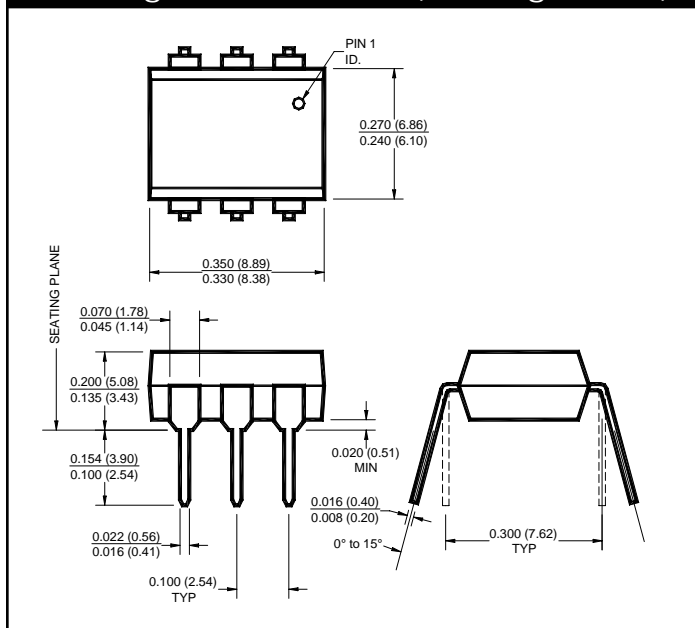
The H11AG1 uses less input power than the neon bulb traditionally used to monitor telephone and line voltages. Additionally, response time can be tailored to ignore telephone dial tap, switching transients and other undesired signals by modifying the value of C2. The high impedance to line voltage also can simply board layout spacing requirements.

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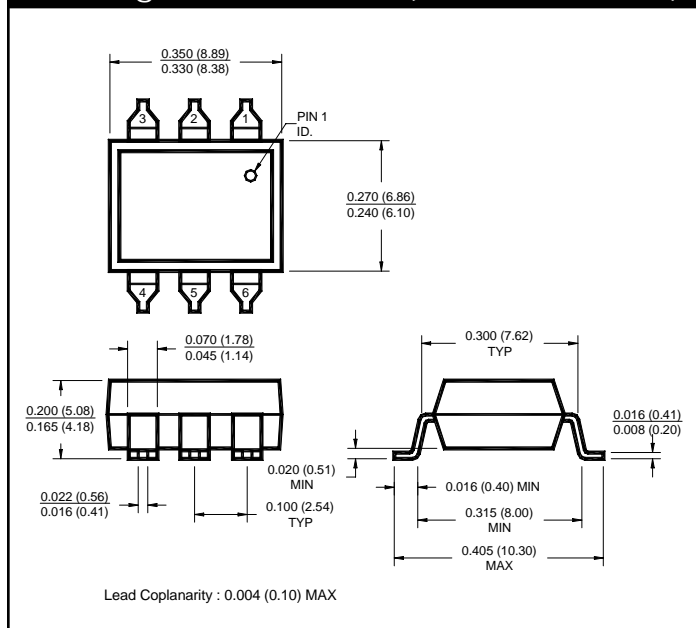
H11AG2

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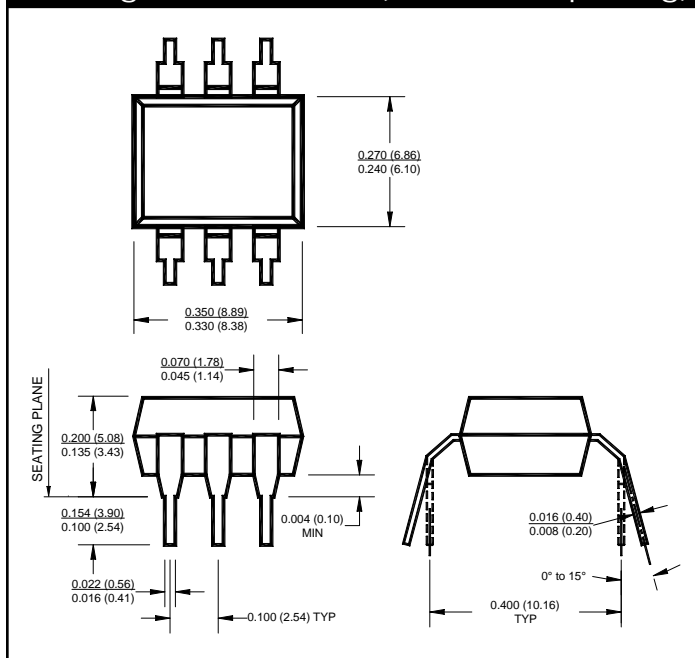
Package Dimensions (Through Hole)



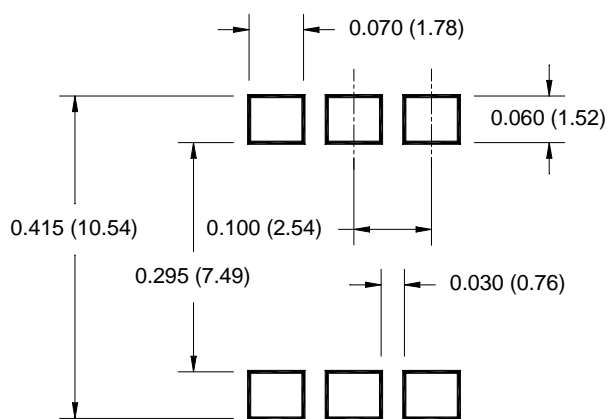
Package Dimensions (Surface Mount)



Package Dimensions (0.4" Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform



NOTE

All dimensions are in inches (millimeters)

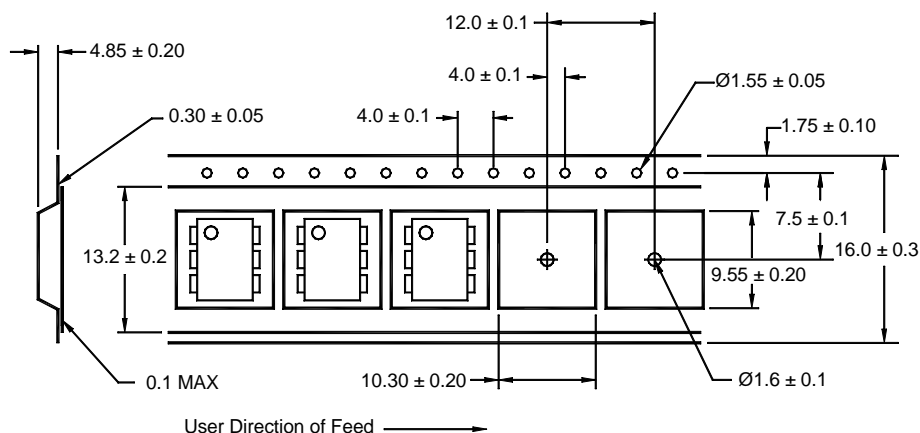
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Option	Order Entry Identifier	Description
S	.S	Surface Mount Lead Bend
SD	.SD	Surface Mount; Tape and reel
W	.W	0.4" Lead Spacing
300	.300	VDE 0884
300W	.300W	VDE 0884, 0.4" Lead Spacing
3S	.3S	VDE 0884, Surface Mount
3SD	.3SD	VDE 0884, Surface Mount, Tape & Reel

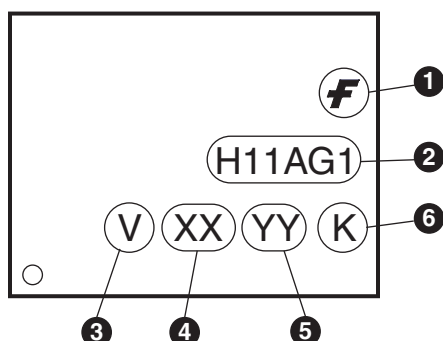
Carrier Tape Specifications ("D" Taping Orientation)



NOTE

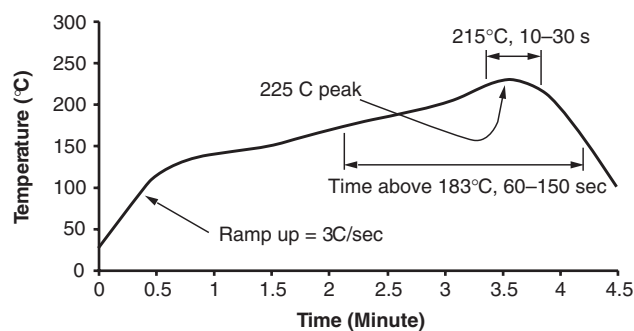
All dimensions are millimeters

MARKING INFORMATION



Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., '03'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Reflow Profile (Black Package, No Suffix)



- Peak reflow temperature: 225°C (package surface temperature)
- Time of temperature higher than 183°C for 60–150 seconds
- One time soldering reflow is recommended

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